IN THE UNITED STATES PATENT AND TRADEMARK OFFICE 1 9 OCT 2004

IN RE APPLICATION OF: Young Hoon PARK, et al.

FOR: APPARATUS AND METHOD FOR DEPOSITING THIN FILM ON WAFER USING REMOTE PLASMA

PRELIMINARY AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Prior to the Examiner acting in the above-referenced application, please preliminary amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.